IN THE CLAIMS

Please amend the claims as follows.

1. (Currently Amended) An optoelectronic package comprising:

an insulating base having an upper surface~~, wherein the insulating base is adapted to dissipate heat away from the optoelectronic assembly~~;

an optoelectronic device mounted on the upper surface of the insulating base;

a metal layer attached to the upper surface of the insulating base; and

a metal cap having a rim located at a bottom portion thereof;

wherein the metal cap encloses the optoelectronic device and the rim of the metal cap is adapted to attach to the metal layer sealing member to hermetically seal the metal cap to the insulating base, and wherein the metal layer extends past the rim by at least an amount sufficient to receive an electrode.

2. (Original) The optoelectronic package of claim 1, wherein the insulating base has an external surface on the outside of the optoelectronic package.

3. (Original) The optoelectronic package of claim 2, further comprising:

a plurality of vias running from an exterior of the optoelectronic package through the insulating base into an interior of the optoelectronic package.

4. (Original) The optoelectronic package of claim 3, wherein the plurality of vias are electrically coupled to the optoelectronic device.

5. (Original) The optoelectronic package of claim 3, wherein the plurality of vias are held in place by solder.

6. (Original) The optoelectronic package of claim 2, wherein the optoelectronic device is mounted on a submount that is mounted on the upper surface of the insulating base.

7. (Original) The optoelectronic package of claim 2, wherein the metal layer extends at least partially past a top surface perimeter of the insulating base to expose a bottom surface of the metal layer.

8. (Original) The optoelectronic package of claim 7, wherein the metal layer extends at least partially around a side surface of the insulating base to expose a bottom surface of the metal layer.

9. (Original) The optoelectronic package of claim 7, wherein the metal layer extends at least partially around a first side surface of the insulating base to expose a first bottom surface of the metal layer and extends at least partially around a second side surface of the insulating base to expose a second bottom surface of the metal layer, wherein the first side surface is opposite the second side surface.

10. (Original) The optoelectronic package of claim 2, wherein the optoelectronic device is an optical transmitter and/or optical receiver.

11. (Original) The optoelectronic package of claim 2, wherein the metal layer comprises a metallization layer at least partially covering a top surface of the insulating base.

12. (Original) The optoelectronic package of claim 11, wherein the metal layer further comprises a metal sealing member coupled to the metallization layer.

13. - 20. (Canceled)

21. (Previously Presented) An optoelectronic package comprising:

an insulating base having an upper surface;

an optoelectronic device mounted on the upper surface of the insulating base;

a metal cap hermetically sealed to the upper surface of the insulating base to enclose an optoelectronic device; and

a plurality of electrical leads coupled to a first set of vias on a lower surface of the insulating base, the vias running through the insulating base into an interior of the optoelectronic package, wherein the electrical leads are electrically coupled to the optoelectronic device.

22. (Previously Presented) The package of claim 21 including a metal layer attached to the upper surface of the insulating base; and wherein the metal cap includes a metal rim to attach to the metal layer to hermetically seal the metal cap to the insulating base.

23. (Previously Presented) The optoelectronic package of claim 1, wherein the insulating base is coupled to a heat sink.

24. (Previously Presented) The optoelectronic package of claim 1, wherein a housing of the optoelectronic package serves as a heat sink.

25. (Previously Presented) The optoelectronic package of claim 1, wherein the insulating base comprises ceramic.

26. (Previously Presented) The optoelectronic package of claim 1, wherein the insulating base comprises one of alumina, beryllium oxide and aluminum nitride.

27. (Previously Presented) The optoelectronic package of claim 1, wherein the insulating base is substantially planar.

28. (Previously Presented) The optoelectronic package of claim 1, wherein the metal cap includes a transparent portion.

29. (Previously Presented) The optoelectronics package of claim 21 including a second set of vias, formed through the insulating base, adapted to conduct welding current from the metal cap to the insulating base during a welding operation to hermetically seal the metal cap to the insulating base.